

ABSTRACT

A through-via substrate may include a substrate including a first surface and a second surface located opposite the first surface, the substrate including a through hole including a wall surface extending from the first surface to the second surface; a through via including a first end face located at the first surface and a second end face located at the second surface, the through via filling the through hole; and an adhesive layer provided between the through via and the wall surface of the through hole. The through via may include a first layer including the first end face and a second layer including the second end face, the second layer being in contact with the first layer at an interface. The adhesive layer may extend along the wall surface toward the second surface in such a manner as not to reach the second surface. The adhesive layer may include a second end where the adhesive layer extending toward the second surface terminates. The interface may be located between the first surface and the second end of the adhesive layer or between the second surface and the second end of the adhesive layer in a thickness direction of the substrate.